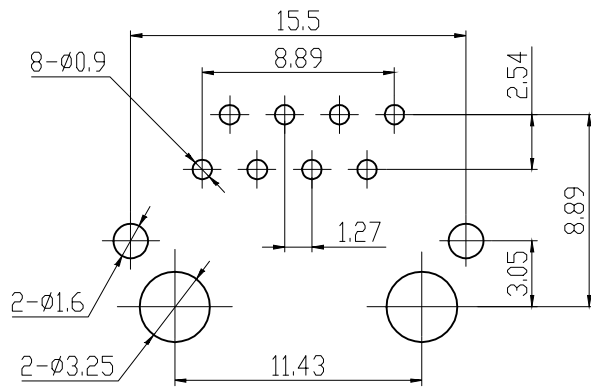
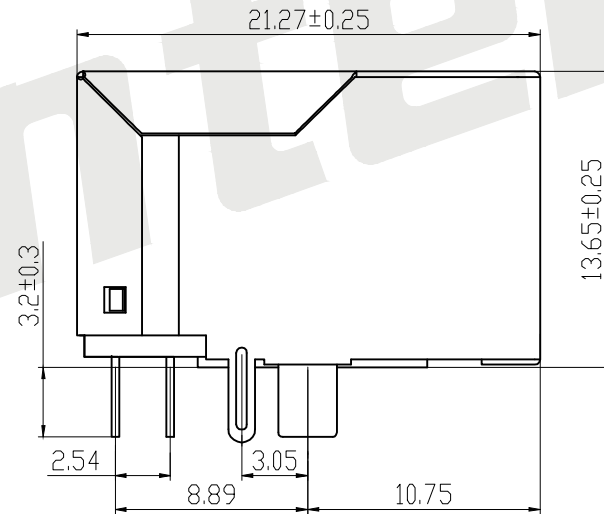
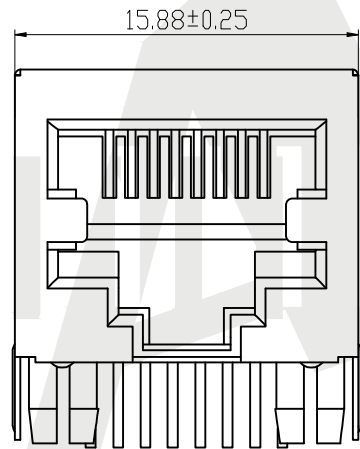
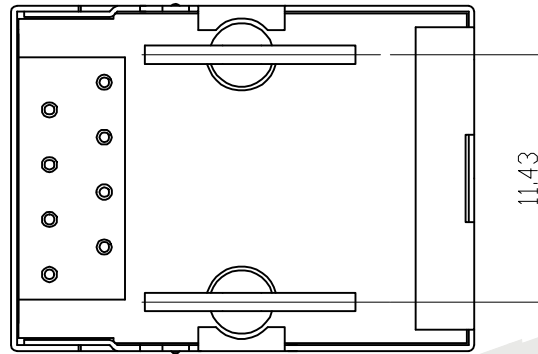


HSF



PC Board Layout



NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125V AC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30 MILLIOHMS MAX
4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVRONMENTAL

1. STORAGE: -40° C TO 85° C
2. OPERATION: 0° C TO 70° C

Order code:

ATRJ5921 - 10P - 8C - X - D - A - D

① ② ③ ④ ⑤ ⑥ ⑦

① SERIES NO:

② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)

③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)

④ Contact Plating

- G0: Gold flash
- G1: 3U" Gold
- G2: 5U" Gold
- G3: 10U" Gold
- G4: 15U" Gold
- G5: 30U" Gold
- SN: Tin

⑥ Ports

- A: 1X1P G: 2X1P
- B: 1X2P H: 2X2P
- C: 1X4P I: 2X3P
- D: 1X5P J: 2X4P
- E: 1X6P K: 2X6P
- F: 1X8P L: 2X8P

⑤ Shield

- A: W/O Shield
- B: Half Shield
- C: Shield W/Eml
- D: Shield W/O Eml

⑦ PCB layout style:

- A: TYPE 1 front legs 3.05
- B: TYPE 1 front legs 3.68
- C: TYPE 1 front legs 4.57
- D: TYPE 2 Back legs 3.05
- E: TYPE 2 Back legs 3.68
- F: TYPE 2 Back legs 4.57

Unless Otherwise specified tolerance	
X. ±0.35	X.XX: ±0.20
X.X: ±0.25	X.XXX: ±0.15

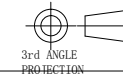
Antenk® ANTENK ELECTRONICS CO., LTD
[Http://www.antenk.com](http://www.antenk.com)
 E-mail: sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

TITLE: RJ45 JACK Side entry, shielded, 1X1P Back 3.05

DRAWING NO: ATRJ5921-10P8C-X-D-A-D

PRODUCT NO: ATRJ5921-10P8C-X-D-A-D



REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		